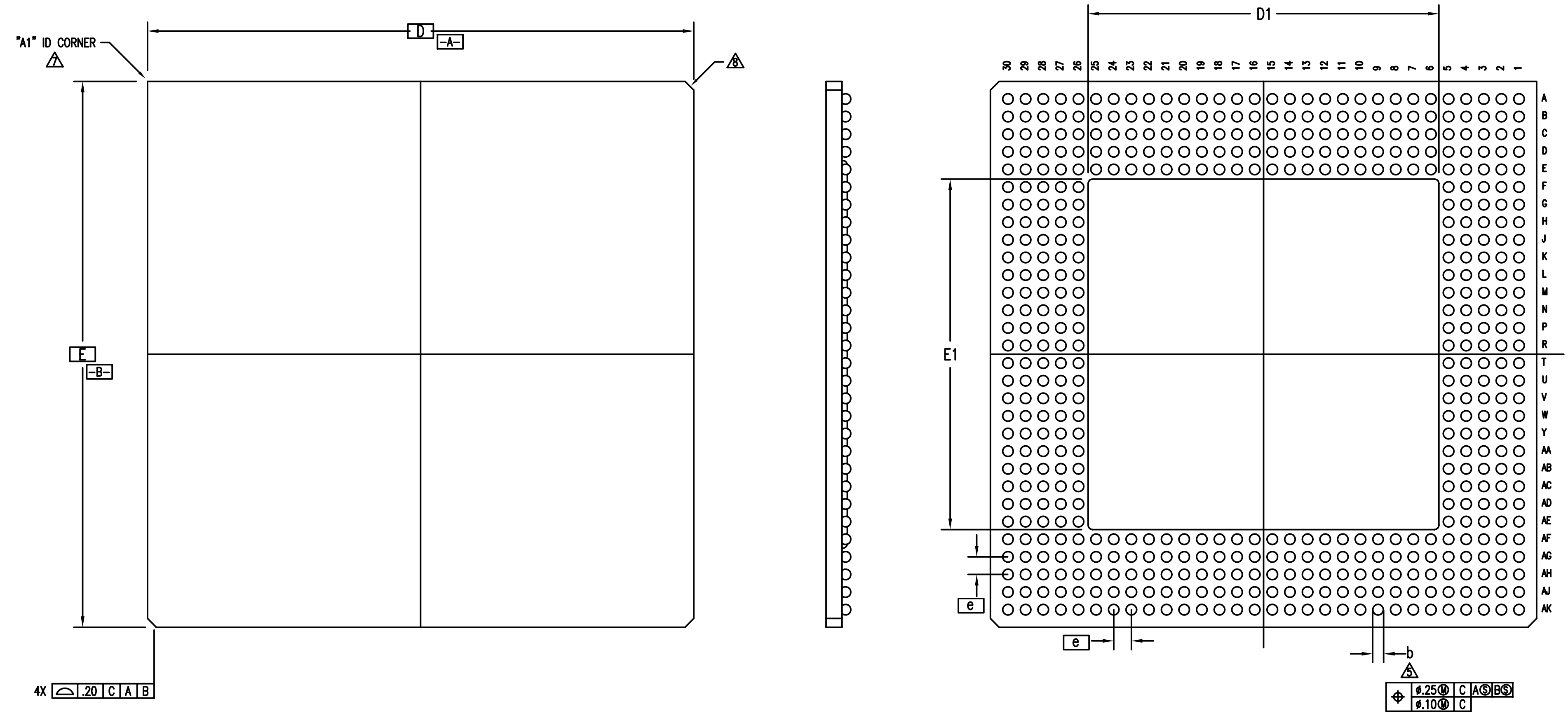
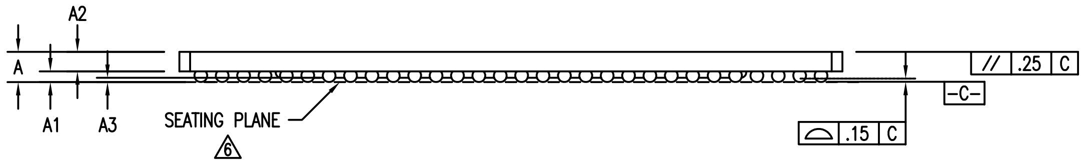
REVISIONS

REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	04/03/06	DP
01	UPDATE COPLANARITY	10/04/07	DP
02	COMBINE POD & LAND PATTERN	06/13/13	KS





TOLERANCES
UNLESS SPECIFIED
DECIMAL ANGULAR
XX± ±
XXX±
XXXX±

IDT Integrated Device Technology, Inc.
www.IDT.com
6024 Silver Creek Valley Road
PHONE: (408) 284-8200
FAX: (408) 284-8591

APPROVALS	DATE
DRAWN DP	04/03/06
CHECKED	

TITLE BX/BXG/RX 500 PACKAGE OUTLINE
31.0 X 31.0 mm BODY
1.0 mm BALLPITCH SBGA

SIZE C
DRAWING No. PSC-4186
REV 02

DO NOT SCALE DRAWING

SHEET 1 OF 3

REVISIONS

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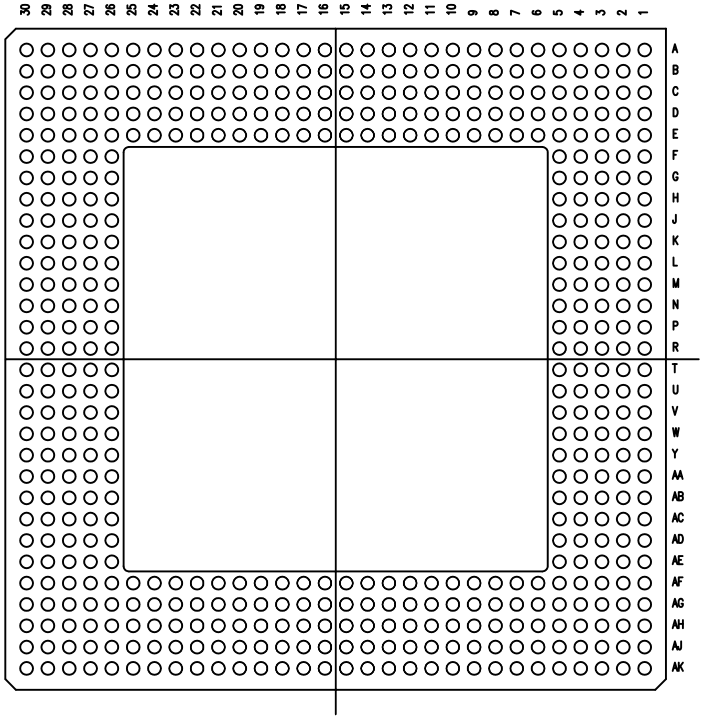

NOTES:

1 ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982

2 "e" REPRESENTS THE BASIC SOLDER BALL GRID PITCH

3 "M" REPRESENTS THE MAXIMUM SOLDER BALL MATRIX SIZE

4 "N" REPRESENTS THE BALLCOUNT NUMBER

5 DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\boxed{-C-}$

6 SEATING PLANE AND PRIMARY DATUM $\boxed{-C-}$ ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS

7 "A1" ID CORNER MUST BE IDENTIFIED BY CHAMFER, INK MARK, METALLIZED MARKING, INDENTATION OR OTHER FEATURE ON PACKAGE BODY

8 EXACT SHAPE OF EACH CORNER IS OPTIONAL

9 ALL DIMENSIONS ARE IN MILLIMETERS

SYMBOL	JEDEC VARIATION			NOTE
	NONE			
	MIN	NOM	MAX	
A	–	–	1.70	
A1	.30	–	–	
A2	.25	–	1.10	
A3	.15	–	–	
D	31.00 BSC			
D1	–	–	19.9	
E	31.00 BSC			
E1	–	–	19.9	
M	30 (DEPOPULATED)			3
N	500			4
e	1.00 BSC			
b	.50	.60	.70	5
CENTER BALL MATRIX	N/A			

TOLERANCES
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SHEET 2 OF 3

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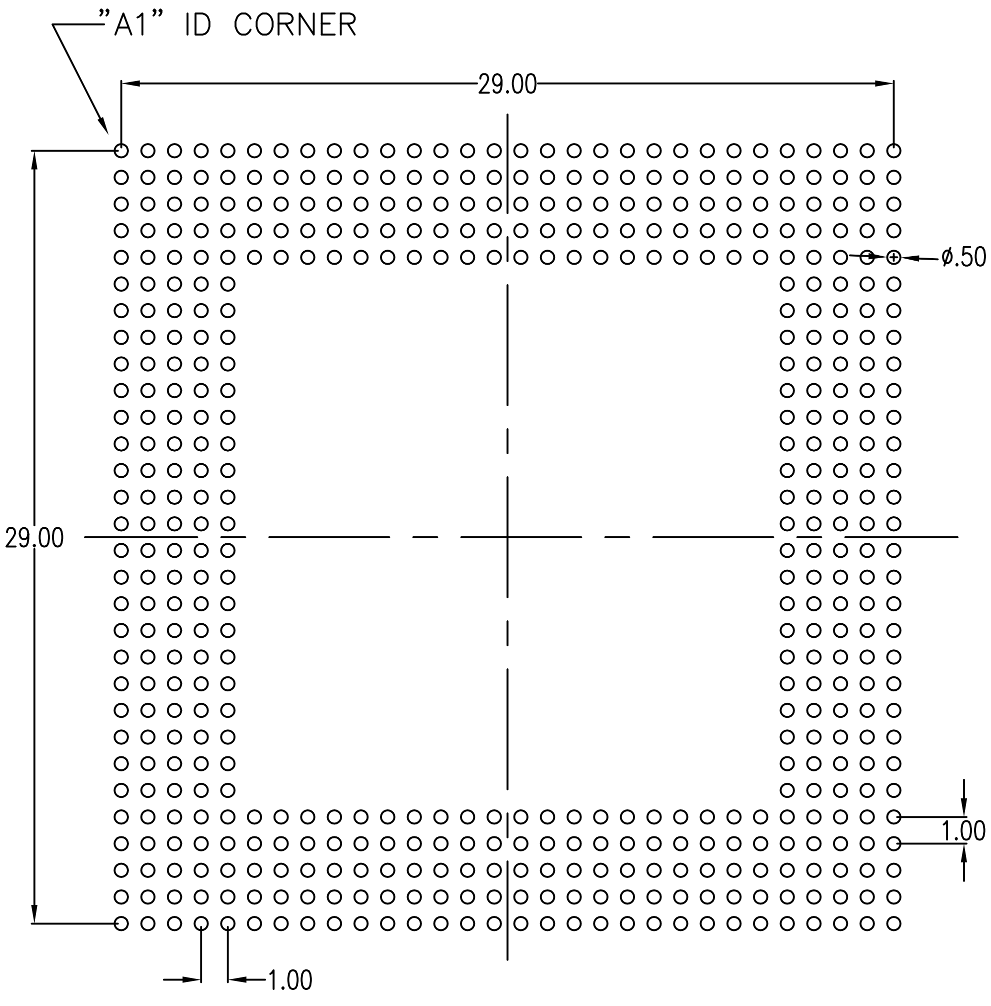

RECOMMENDED LAND PATTERN DIMENSION

NOTE:

1) ALL dimensions are in mm, Angles in degrees.
2) Top down view, as view on PCB.
3) NSMD Land Pattern Assumed
4) Land Pattern Recommendation as per IPC−7351B generic requirement for surface mount design and Land Pattern.

TOLERANCES
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DECIMAL ANGULAR
XX± ±
XXX±
XXXX±

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SIZE	DRAWING No.	REV
C	PSC−4186	02

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SHEET 3 OF 3